

ABSTRACT OF THE DISCLOSURE

A semiconductor assembly comprises a semiconductor package comprising a substrate, a die positioned on the substrate, and a lid positioned on the die. A receiver receives the semiconductor package. A clamp engages the lid of the semiconductor package and the receiver and applies a clamping force to the lid of the semiconductor package to hold the semiconductor package to the receiver. A spring member having a clamp contact portion and a substrate contact portion is positioned between the clamp and the substrate of the semiconductor package so that the clamp contact portion of the spring member contacts the clamp and so that the substrate contact portion of the spring member contacts the substrate of the semiconductor package, the spring member transferring a portion of the clamping force from the lid of the semiconductor package to the substrate of the semiconductor package.